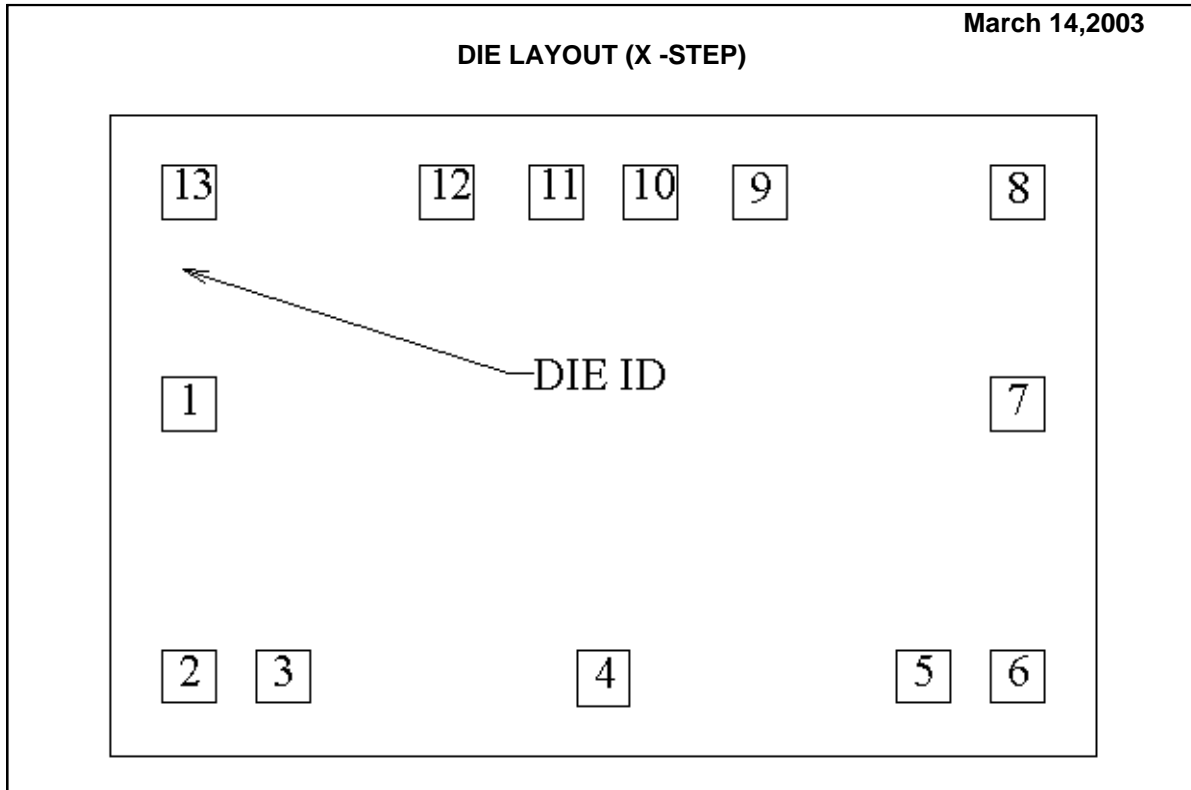


**LM747 MDC MWC
DUAL OPERATIONAL AMPLIFIER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	747	Bond Pad Opening Size (min)	86µm x 86µm
Die Step	X	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1041µm x 1600µm 41.0mils x 63.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	152µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (X -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT A-	1	-673	51	86	x	86
INPUT A	2	-673	-391	86	x	86
OFFSET NULL A	3	-521	-391	86	x	86
V-	4	0	-394	86	x	91
OFFSET NULL B	5	521	-391	86	x	86
INPUT B	6	673	-391	86	x	86
INPUT B-	7	673	51	86	x	86
OFFSET NULL B	8	673	396	86	x	86
V+	9	254	396	86	x	86
OUTPUT B	10	76	396	86	x	86
OUTPUT A	11	-76	396	86	x	86
V+	12	-254	396	86	x	86
OFFSET NULL A	13	-673	396	86	x	86

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